

nano SIM push-pull type connector

1.Introduction

1.1 Objective

Testing was performed on the nano SIM push-pull type connector to determine

if it meets the requirement of product specification, 108-140328

1.2 Scope

This report covers the electrical, mechanical and environment performance requirements of the nano SIM push-pull type connector.

The qualification testing was performed between 28APR2023 and 25MAY2023.

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

1.3 Conclusion

The nano SIM push-pull type connector meets the electorical, mechanical and environmental performance requirements of design objective, 108-140328

1.4 Test samples

Samples were taken randomly from prototype samples. The follwing samples were used.

Product Part No.	Description
2452808-1	nano SIM push-pull type connector

Appendix 1



2. Test contents

Para.	Test Items	Requirements	Judgment					
2.1	Examination of product	Visual inspection	Acceptable					
		No physical damage						
		Electrical Requirements						
2.2	Contact resistance (Low level)	t resistance Mate connector with dry circuit (20mV, 100mA max.)						
		4-wire measurement required						
		Resistance of termination wires shall be deducted from the reading						
		Refer to fig.4 for measurement method						
		(IEC 60512-3-1)						
2.3	Insulation resistance	Unmated connector with 100 VDC between adjacent contact for 1 minute (IEC 60512-3-1)	Acceptable					
2.4	Dielectric withstanding voltage	Unmated connector with 500 VAC between adjacent contact for 1 minute (IEC 60512-3-1)	Acceptable					
2.5	Temperature rise	Contacts series apply test current of loaded rating current of the circuit and measure the temperature rising by probing on soldered areas of contacts, after the temperature becomes stabilized deduct ambient temperature from the measured (EIA-364-70A)	Acceptable					

Fig. 1 (CONT.)



Qualification Test Report

Para.	Test Items	Requirements	Judgment
		Mechanical Requirements	
2.6	Mating force	Card inserts connector Operation speed: 10mm/min	Acceptable
2.7	Un-mating force	Pull out of the card from Connector Operation speed: 10mm/min	Acceptable
2.8	Durability (1500 cycle)	[Operation speed] Mechanically operated: 500 cycles/hour Manually operated: 200 cycles/hour including pause between mate/un-mate to 1500 cycles After every 10 (max.) cycles blow with dry air	Acceptable
		Environmental Requirements	
2.9	Vibration	Apply for 2 hours in each 3 mutually perpendicular axes (total 6 hours) Frequency=10-55-10 Hz (Sweep time: 1 minute max.) Amplitude=1.52mm, Current=100mA [EIA-364-28E Condition I]	Acceptable
2.10	Shock	Apply 3 successive shocks in each direction along the 3 mutually perpendicular axes (total 18 shocks) Pulse shape=half sine Peak acceleration=490m/s ² (50G) Duration of pulse=11ms [EIA-364-27B Condition I]	Acceptable

Fig. 1 (CONT.)



Para.	Test Items	Requirements	Judgment
2.11	Temperature life	+85°C for 98 hours; recovery period 1-2hours under ambient atmospheric conditions (IEC60068-2-2Bb)	Acceptable
2.12	Thermal shock (Change of temperature)	$T_a = -40 \text{ °C}$ for 30 min; then change of temp=25 °C, maximum 5 min; then $T_b=+85 \text{ °C}$ for 30min for 26cycles Recovery: 2 hours at ambient atmosphere (IEC60068-2-14 Test Na)	Acceptable
2.13	Humidity - temperature cycling	Temp 25-65°C, RH 90-95% for 10 cycles Recovery: 2 hours at ambient atmosphere (EIA-364-31)	Acceptable
2.14	Salt spray	48 hours spray at temp.35°±2°C, R/H 90-95%, Salt NaCl mist 5% After test, parts and cards are washed and return to room ambient for 2 hours	Acceptable
2.15	SO2 gas	10±3ppm, Damp 75% at 40±2°C, 48hours	Acceptable
2.16	Solderability	Peak Temperature: 240°C±5°C, Reflow Time (230°C Min): 25~50 seconds	Acceptable



3. Product Qualification Test Sequence

		Test Group								
Para.	Test Examination	А	В	С	D	Е	F	G	Н	
					Test S	Sequen	ce (a)		1	
3.5.1	Examination of product	1,9	1,7	1,5	1,5	1,3	1,10	1,9	1,8	1,3
3.5.2	Contact resistance (Low level)	2,6	2,4,6	2,4	2,4		2,7		2,5,7	
3.5.3	Insulation resistance							2,7		
3.5.4	Dielectric withstanding voltage							3,8		
3.5.5	Temperature rise					2				
3.5.6	Mating force	3,7					3,8			
3.5.7	Un-mating force	4,8					4,9			
3.5.9	Durability	5					5	4	3	
3.5.10	Vibration		3							
3.5.11	Shock		5							
3.5.12	Temperature life						6			
3.5.13	Thermal shock (Change of temperature)							5	4	
3.5.14	Humidity-temperature cycling							6	6	
3.5.15	Salt spray			3						
3.5.16	SO2 gas				3					
3.5.17	Solderability									2

(a) Numbers indicate sequence in which the tests are performed.

Fig. 2



4. Test Results

Measure Item	n	Unit		Result	S		Requirement	Judgment
			Max.	Min.	Ave.	Sig.		

Test group A												
Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable				
Contact resistance	18	mΩ	25.52	9.11	14.75	5.85	50 mΩ MAX	Acceptable				
Mating force	3	Ν	2.49	1.48	1.90	0.53	10N MAX	Acceptable				
Un-mating force	8	Ν	2.83	1.50	2.12	0.67	1~10N	Acceptable				
Durability	3	-		No disc	ontinuity		No abnormalities	Acceptable				
Contact resistance	18	mΩ	25.66	9.07	15.58	5.44	100mΩ MAX	Acceptable				
Mating force	3	Ν	5.67	3.19	4.43	1.24	10N MAX	Acceptable				
Un-mating force	3	Ν	6.23	3.62	5.10	1.34	1~10N	Acceptable				
Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable				

	Test group B													
Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable						
Contact resistance	3	mΩ	21.96	9.17	50 mΩ MAX	Acceptable								
Vibration	3	-		No disc	ontinuity		1µs MAX	Acceptable						
Contact resistance	18	mΩ	22.89	8.95	13.86	4.98	100mΩ MAX	Acceptable						
Shock	3	-		No disc	ontinuity		1µs MAX	Acceptable						
Contact resistance	18	mΩ	22.54	9.26	14.03	4.72	100mΩ MAX	Acceptable						
Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable						

Test group C												
Examination of product	3	-		No abno	Acceptable							
Contact resistance	3	mΩ	21.68	8.32	13.57	4.66	$50m\Omega$ MAX	Acceptable				
Contact resistance after salt spray	18	mΩ	22.63	6.96	14.54	4.68	100mΩ MAX	Acceptable				
Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable				



Qualification Test Report

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Measure Item	n	Unit		Result	S		Requirement	Judgment
			Max.	Min.	Ave.	Sig.	ľ	

Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable
Contact resistance	18	mΩ	20.03	8.77	13.10	4.07	50mΩ MAX	Acceptable
Contact resistance After SO2 gas	18	mΩ	20.46	9.24	13.78	4.08	100mΩ MAX	Acceptable
Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable

Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable
Temperature rise	3	°C	6.19	6.01	6.10	0.09	30°C MAX	Acceptable
Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable

Test group F								
Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable
Contact resistance	18	mΩ	19.75	8.26	13.07	4.05	50mΩ MAX	Acceptable
Mating force	3	Ν	1.93	1.77	2.19	0.21	10N MAX	Acceptable
Un-mating force	3	Ν	2.35	1.87	2.11	0.24	1~10N	Acceptable
Durability	3	_		No disc	ontinuity		No abnormalities	Acceptable
Contact resistance after Temperature life	18	mΩ	20.78	8.85	13.52	4.18	100mΩ MAX	Acceptable
Mating force	3	Ν	3.92	3.46	3.70	0.23	10N MAX	Acceptable
Un-mating force	3	Ν	4.58	4.22	4.42	0.18	1~10N	Acceptable
Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable

Fig. 3 (CONT.)



Measure Item	n	Unit	Results				Bequirement	Judament		
			Max.	Min.	Ave.	Sig.	rioquionioni	oddgmont		
Test group G										
Examination of product	3	-	No abno	ormalities	;		No abnormalities	Acceptable		
Insulation resistance	3	Ω	523 x 10) ¹³ Ω Mi	n.		1000MΩ Min.	Acceptable		
Dielectric strength	3	-	No abno	ormalities	;		No abnormalities	Acceptable		
Insulation resistance after Durability, Thermal shock and Humidity-temperature cycling	3	Ω	313 x 10) ¹³ Ω Mi	'n.		1000MΩ Min.	Acceptable		
Insulation resistance after Durability, Thermal shock and Humidity-temperature cycling	3	-	No abno	ormalities			No abnormalities	Acceptable		
Insulation resistance after Durability, Thermal shock and Humidity-temperature cycling	3	-	No abno	ormalities	i		No abnormalities	Acceptable		

Test group H									
Examination of product	3	-		No abno	ormalities		No abnormalities	Acceptable	
Contact resistance	18	mΩ	21.06	8.82	13.50	4.55	$50m\Omega$ MAX	Acceptable	
Durability	3	-		No disco	ontinuity		No abnormalities	Acceptable	
Contact resistance after Thermal shock	18	mΩ	22.08	9.13	14.28	4.65	100mΩ MAX	Acceptable	
Contact resistance After Humidity-temperature cycling	18	mΩ	21.87	9.63	14.53	4.51	100mΩ MAX	Acceptable	
Examination of product	3	-	No abnormalities				No abnormalities	Acceptable	

Fig. 3 (CONT.)



Measure Item	n	Unit	Result	Requirement	Judgment				
Test group I									
Examination of product	-	3	No abnormalities	No abnormalities	Acceptable				
Solderability	-	3	More than 95% of tested area was covered with wet solder	Minimum 95% solder	Acceptable				
Examination of product after test	-	3	No abnormalities	No abnormalities	Acceptable				

Fig. 3 (END)